

Velox™ 3.3 Highlights

Probe Station Control Software

Velox 3.3 is the next big step in improving our probe station software for greater usability. The new Wafer Map comes with a modernized user interface and unique patented functions that make workflows more intuitive and logical. SubDie handling has been simplified in cooperation with some of our key customers. Additionally, the Velox Help has been completely re-designed for more intuitive navigation and problem-solving.

Free Velox updates are possible without the need of a Service visit.*

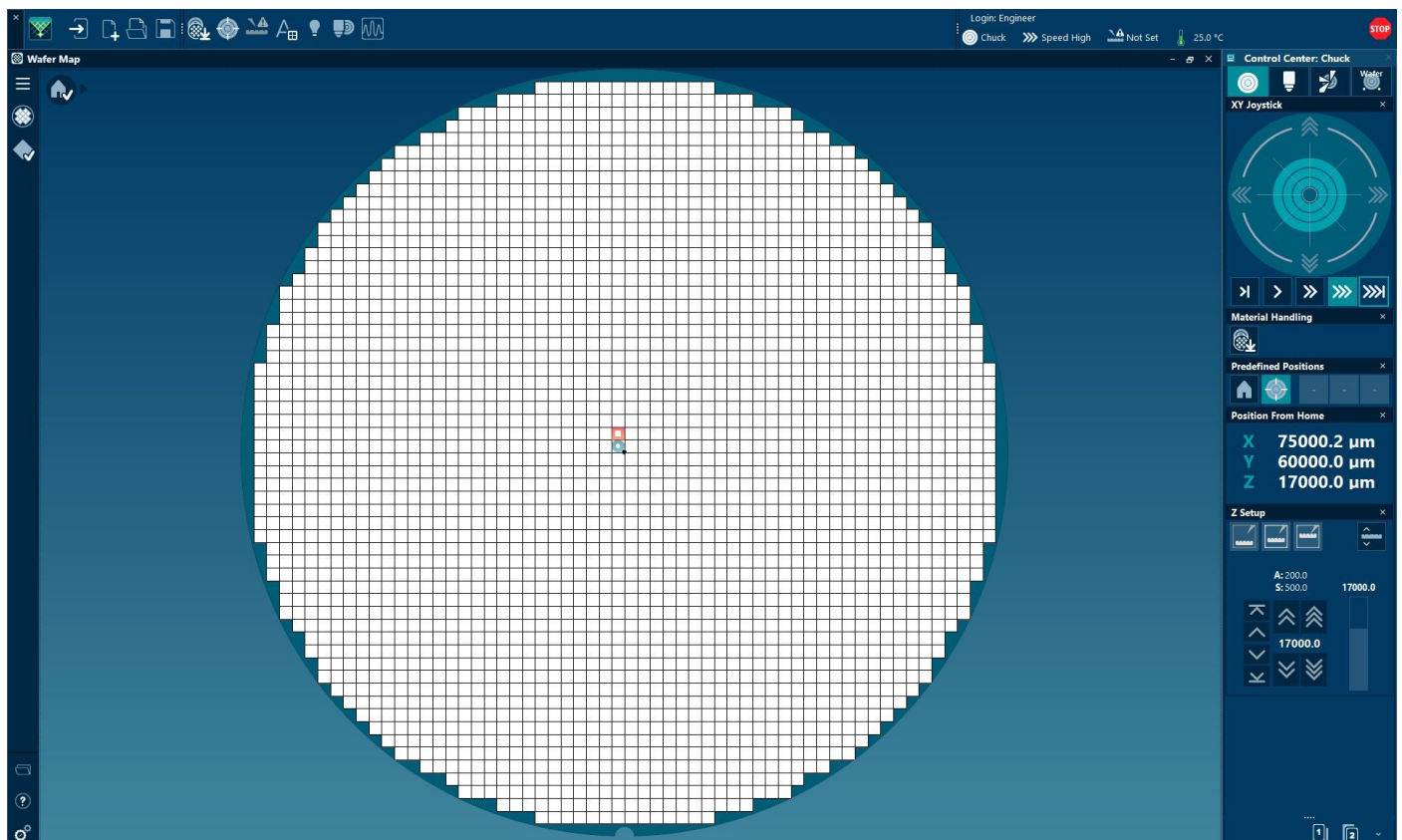


New Wafer Map

- / New modern and intuitive user interface
- / **Floating action buttons** for faster access to most important functions like *Step Next Die* and *Set Home*
- / Logical, simplified **workflows**
- / Patented selective **Die Soaking** and **Die Alignment**
- / Optimized **SubDie handling**
- / **Z-profiling** has been simplified and is now integrated in Wafer Map
- / Support of **SEMI G85** wafer map files

Benefit:

Intuitive, ergonomic operation with significantly less training needs.



Die Soaking

Fixed ☒ 0 h 20 min 0 s

Dynamic ☒ 0 h 5 min 5 s

Use Selective Die Soaking ☒

Die Selection Mode (i)

☒ Invert Selected Dies

☐ Add Selected Dies

☐ Remove Selected Dies

Die Soaking Border Area (mm)

Soak Every Nth Center Die

Auto-Mark Dies

Dies for soaking: 20
 Dies for probing: 52
 Soak time savings at 80 °C: 9587 Minutes

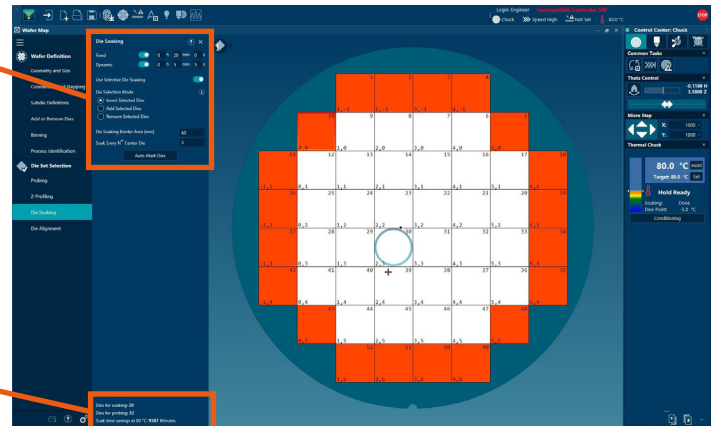
Selective Die Soaking

- / New level of wafer testing efficiency for non-ambient probing
- / User can define soak times for each die
- / Easy-to-use graphical interface



Benefit:

Significantly faster time to data through smarter automation.



Selective Die Alignment

- / User can define which dies need alignment
- / No complex adaptations of the Test Executive necessary



Benefit:

Significantly faster time to data through smarter automation.

Die Alignment

Use Vision Assisted Stepping ☒

XYZ Theta alignment using eVue/Scope.

Train Alignment Tool

Use Selective Die Alignment ☒

Die Selection Mode (i)

☒ Invert Selected Dies

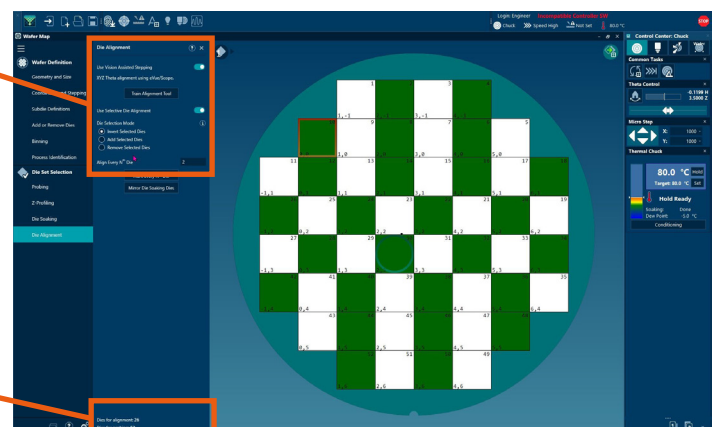
☐ Add Selected Dies

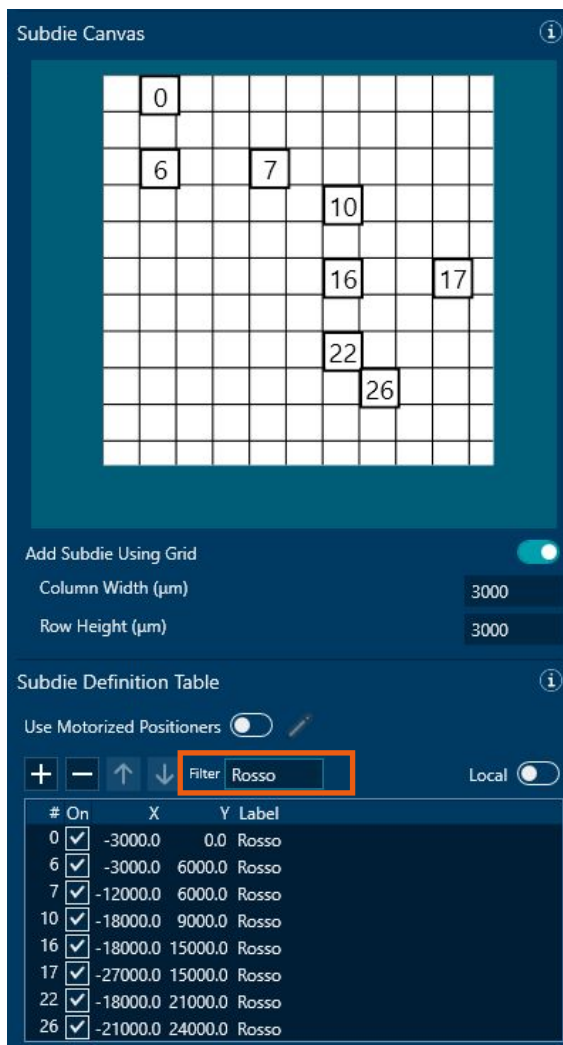
☐ Remove Selected Dies

Align Every Nth Die

Mark Every Nth Die

Dies for alignment: 26
 Dies for probing: 52

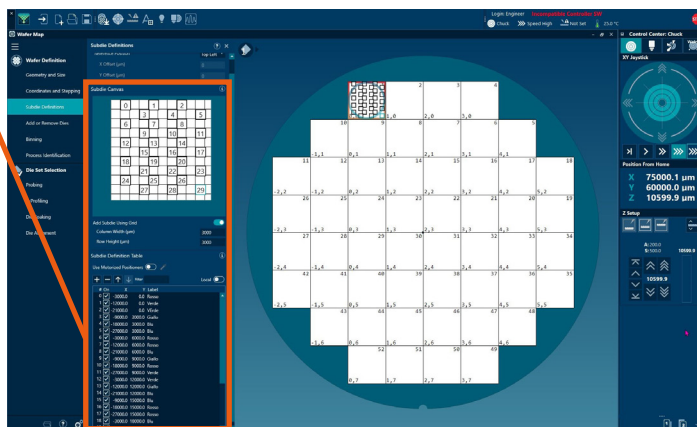




Sub Die Handling

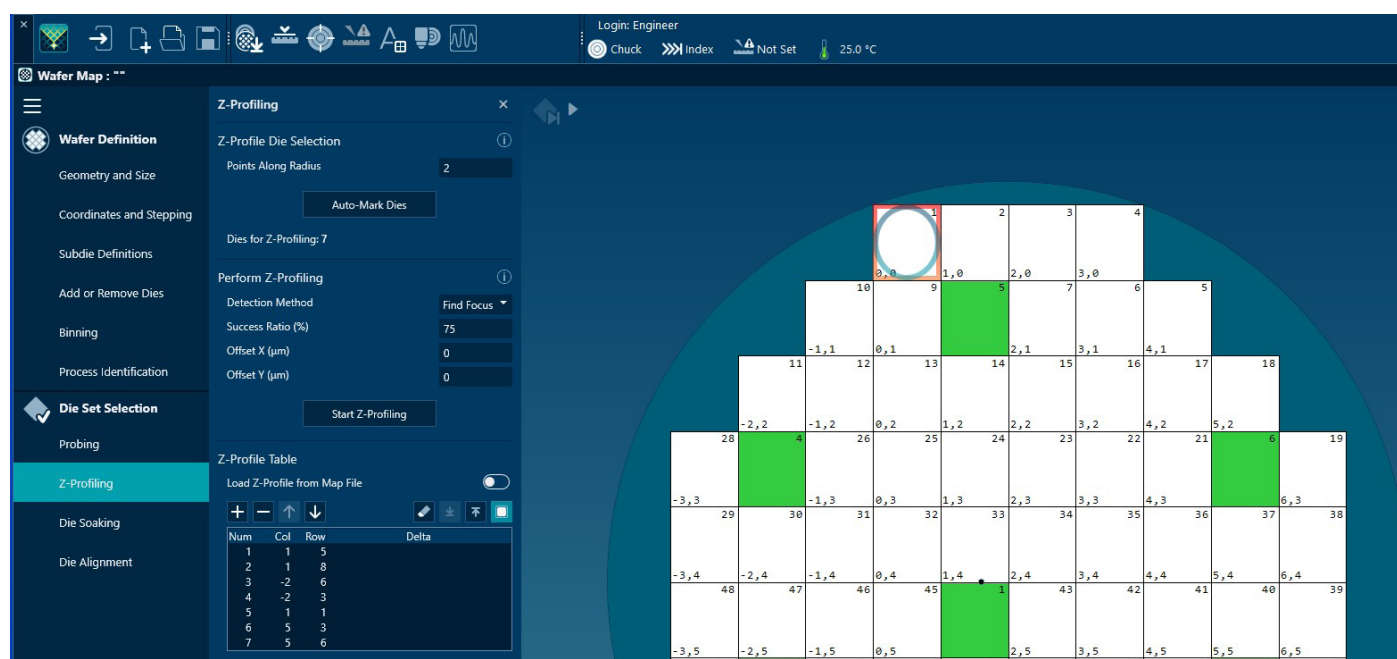
- / Sub Dies can be labeled with different colors for better differentiation
- / Drag/drop Sub Dies to different positions in table
- / Select multiple Sub Dies in table
- / Filter by labels

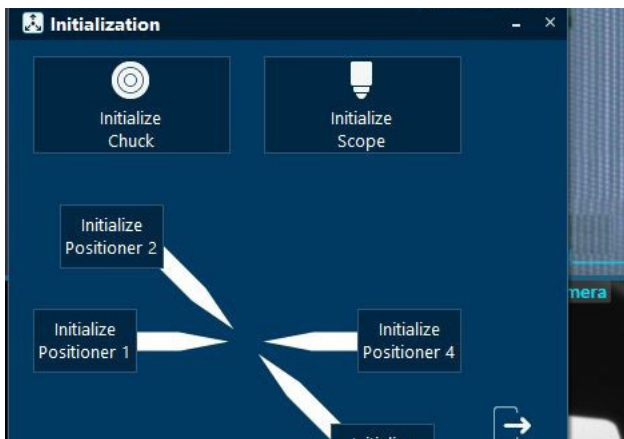
Benefit:
Easier handling of multiple Sub Dies.



Z-Profiling

- / Z-Profiling tool integrated in Wafer Map
- / No additional application necessary





Initialization Tool

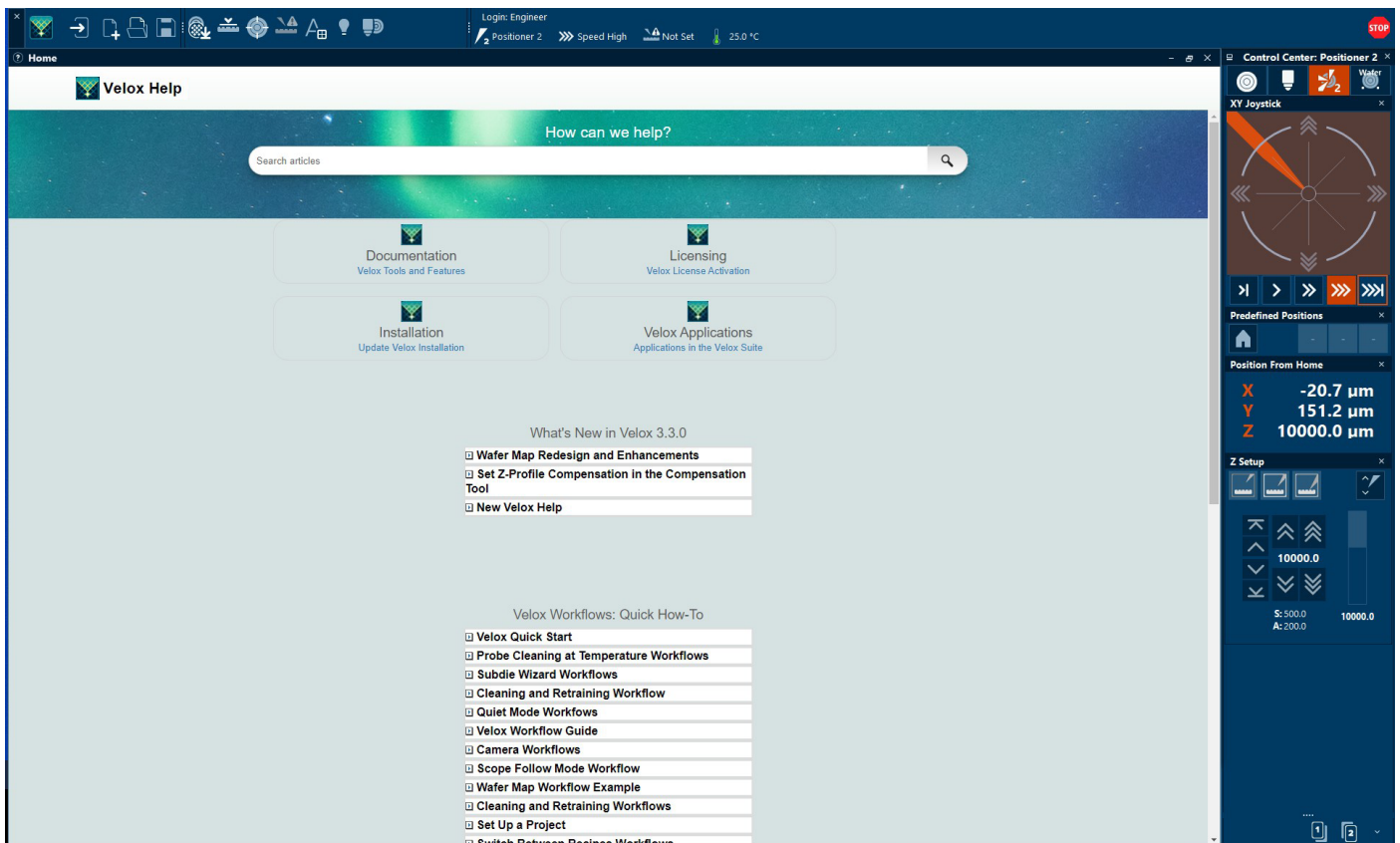
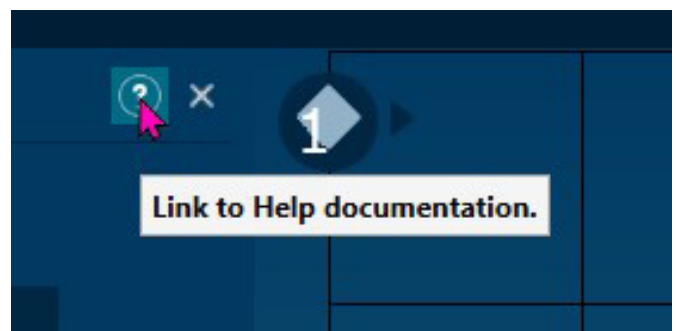
- / Calibration of chuck stage, microscope stage and motorized positioners
- / Can be done by the user, no FormFactor service needed
- / Self-explaining user interface

Benefit:

Less training needed. Faster setup times.

New Velox Help

- / Velox Help has been re-designed to provide easier access
- / Improved search function
- / Access help directly from Velox
- / Workflows, Quick How-To, Frequently Asked Questions and more



* Requires Velox 3.1 or later and latest PC hardware. Please contact your local service person for more information.